

Title (en)

ENCAPSULATION SYSTEM FOR AN OPTOELECTRONIC COMPONENT COMPRISING AT LEAST A FIRST ENCAPSULATION AND A SECOND ENCAPSULATION, AND OPTOELECTRONIC COMPONENT COMPRISING AN ENCAPSULATION SYSTEM OF THIS KIND

Title (de)

VERKAPSELUNGSSYSTEM FÜR EIN OPTOELEKTRONISCHES BAUELEMENT MIT MINDESTENS EINER ERSTEN VERKAPSELUNG UND EINER ZWEITEN VERKAPSELUNG, OPTOELEKTRONISCHES BAUELEMENT MIT EINEM SOLCHEN VERKAPSELUNGSSYSTEM

Title (fr)

SYSTÈME D'ENCAPSULATION CONÇU POUR UN COMPOSANT OPTOÉLECTRONIQUE, COMPORTANT AU MOINS UNE PREMIÈRE ENCAPSULATION ET UNE DEUXIÈME ENCAPSULATION, COMPOSANT OPTOÉLECTRONIQUE ÉQUIPÉ D'UN TEL SYSTÈME D'ENCAPSULATION

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2021139853A1] The invention relates to an encapsulation system (1), in particular a double encapsulation, for an optoelectronic component (2), comprising at least a first encapsulation (3) and a second encapsulation (4), the first encapsulation (3) being formed from at least a front barrier layer (5) on a front side of the optoelectronic component (2) and at least a rear barrier layer (6) on a rear side of the optoelectronic component (2) with at least a first connection material (7) mounted in-between, the second encapsulation (4) being formed from at least a front protection layer (8) on the front side of the optoelectronic component (2) and at least a rear protection layer (9) on the rear side of the optoelectronic component (2) with at least a second connection material (10) mounted in-between. The first encapsulation (3) surrounds the optoelectronic component (2) in such a way that the first encapsulation (3) protrudes by a first edge region (11) from the optoelectronic component (2), and the second encapsulation (4) encloses the first encapsulation (3) with the optoelectronic component (2) in such a way that the second encapsulation (4) protrudes by a second edge region (12) beyond the first edge region (11) of the first encapsulation (3).

IPC 8 full level

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Citation (search report)

See references of WO 2021139853A1

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DOCDB simple family (publication)

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